

IN THE CLAIMS:

The following listing of claims will replace all prior versions, and listings, of the claims in the application:

1. (Canceled)

2. (Currently amended) The lead frame substrate according to claim 4 5, wherein said semiconductor die pad, said plurality of termination pads, and said plurality of connection bars comprise a thermally and electrically conductive material.

3. (Original) The lead frame substrate according to claim 2, wherein said thermally and electrically conductive material comprises copper.

4. (Canceled)

5. (Previously presented) A lead frame substrate, comprising:
a plurality of connection bars;
a semiconductor die pad being adapted to receive a semiconductor die;
a plurality of termination pads being linked together and to said semiconductor die pad by said plurality of connection bars, each one of said plurality of termination pads being adapted to receive a passive component and a bonding wire; and
a molding compound fixing said semiconductor die pad, said plurality of termination pads, and said plurality of connection bars together;
wherein said semiconductor die pad, said plurality of termination pads, and said plurality of connection bars include a top and bottom surface, and said molding compound leaves said top and bottom surfaces uncovered.

6. (Currently amended) The lead frame substrate according to claim 4 5, wherein said semiconductor die pad, said plurality of termination pads, and said plurality of connection bars have a unitary construction from a common piece of material.

7. (Currently amended) The lead frame substrate according to claim 4 5, further comprising a plurality of leads located around a periphery of the lead frame substrate.

8. (Currently amended) The lead frame substrate according to claim 4 5, wherein said at least one permanent connection bar electrically couples said semiconductor die pad to at least one of said plurality of termination pads.

9. (Currently amended) The lead frame substrate according to claim 4 5, wherein said at least one permanent connection bar electrically couples selected ones of said plurality of termination pads together.

10. (Previously presented) The lead frame substrate according to claim 5, wherein said plurality of connection bars comprises permanent connection bars and temporary connection bars.

11. (Previously presented) The lead frame substrate according to claim 10, wherein said temporary connection bars are adapted to be removed from the lead frame substrate after said molding compound has fixed said semiconductor die pad, said plurality of termination pads, and said plurality of connection bars together.

12. (Currently amended) The lead frame substrate according to claim 4 5, wherein the lead frame substrate comprises a substantially uniform thickness.

13. (Currently amended) The lead frame substrate according to claim 4 5, wherein the lead frame substrate is adapted for being mounted to a circuit board.

14. (Previously presented) The lead frame substrate according to claim 13, wherein only said semiconductor die pad and said plurality of leads contact the circuit board when the lead frame substrate is mounted on the circuit board.

15-60. (Canceled)